

IN THE SPECIFICATION

Please insert the following heading on page 1, before prenumbered line 4:

FIELD OF THE INVENTION

Please insert the following heading on page 1, before prenumbered line 9:

DISCUSSION OF THE BACKGROUND

Please insert the following heading on page 3, before prenumbered line 9:

SUMMARY OF THE INVENTION

Please replace the paragraph beginning at page 4, line 6, with the following rewritten paragraph:

In a first embodiment, the structure, with the conducting element deposited on the backing sheet, is characterized in that the element is sandwiched between the tie sheet and the backing sheet, and at least the tie sheet is, on at least on of its sides, placed so as to be set back relative to the associated free edge of he transparent substrate so as to leave space for a free part of the transparent substrate and for an exposed portion of the conducting element, this free part facing the exposed portion of the conducting element, and in that the connection means are fastened by adhesive bonding to the free part of the substrate and are connected via electrical bonding means to that exposed portion of the conducting element facing the free part.

Please replace the paragraph beginning at page 13, line 17, with the following rewritten paragraph:

Thus, according to the invention, ~~one~~ at least one of the backing sheet 31 of the conducting element, the tie sheet 22 and the additional sheet 23 or the covering sheet 24, when one is present, is, at least on one of its sides, placed set back toward the interior of the

structure relative to the associated free edge of ~~its~~ the first substrate 20 so as to leave a portion 32 of the conducting element bare or exposed on at least one of the faces 30a or 30b thereof. The connection means 40 that connect the conducting element 30 to the electrical ground of the display are advantageously a flat conductor such as a busbar or a conductive foam tape that is connected to the exposed portion 32 of one of the faces 30a or 30b of the conducting element 30 by adhesive bonding or by mechanical clamping.